Sheet	1	of	1	
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Form PTO-1449 US Dept. of Commerce (REV. 8-83) PATENT & TRADEMARK OFFICE			ATTY DOCKET NO. 116753		APPLICATION NO. 10/630,862						
INFO	RMATI	ON DISCLOSURE STATEMENT						j			
(Use several sheets if necessary)  APPLICANT(S)  Masahiro KOJIMA et al.											
NOV 2 2 2005 &			8 8	FILING DATE July 31, 2003		GROUP 1754					
PATENT DOCUMENTS											
EXAMINER INITIAL	EXAMINER		DATE		NAME		CLASS	SUB CLASS			
CC	1	6,809,042	10/	26/2004	KOJIMA et al.						
	2	U.S. Pub. No. 2004/0110641	6/1	0/2004	KOJIMA et al.						
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	4	4,968,664	11/	6/1990	SUGIHAVA et al.						
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		DOCUMENT NUMBER		DATE	COUNTRY		CLASS	SUB CLASS			
CC	6	JP 2004-026625 (with Abstract and machine translation)	1/29/2004		JAPAN						
	7	JP 06-318412 (with Abstract and machine translation)	11/	15/1994	JAPAN						
	8	JP 02-199023 (with Abstract)	8/7.	/1990	JAPAN						
	9	DE 203 15 783	2/2	6/2004	GERMANY						
	10	EP 0 412 199	2/1	3/1991	EUROPE						
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		OTHER DOCUMENTS (Inc	cludir	ng Author,	Title, Date, Pertinent Pages, etc.)						
CC	K. Ohbayashi et al., "High-T <sub>c</sub> (95 K) As-Grown Superconducting Bi-Sr-Ca-Cu-O Thin Films", Japanese Journal of Applied Physics, Part 2 (Letters), Vol. 29, No. 11, pages L2049-L2052, November 1990										
	↓				<del></del>						
CL	13	N. H. Sinh, "Properties of the Bi-Surplus Superconducting Bi <sub>2.1-x</sub> Pb <sub>x</sub> Sr <sub>2</sub> Ca <sub>2</sub> Cu <sub>3</sub> O <sub>y</sub> Compounds", Journal of Magnetism and Magnetic Materials, Vol. 262, No. 3, pages 514-519, June 2003									
<u> </u>	<del>                                     </del>	·									
	<del> </del>					·					
EXAMINER Blue P. Cook DATE CONSIDERED 5/11/06											
Examiner: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.											

Date: November 22, 2005